Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.40mil		
4	Dielectric1	FR-4 High TG	12.60mil	4.8	
5	MidLayer1	Copper	1.40mil		
6	Dielectric2	FR-4 High TG	30.00mil	4.8	
7	MidLayer2	Copper	1.40mil		
8	Dielectric3	FR-4 High TG	12.60mil	4.8	
9	Bottom Layer	Copper	1.40mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				

Symbol	Hit Count	Tool Size	Plated	Hole Type
○	13	7.874mil (0.2mm)	PTH	Round
▽	370	10mil (0.254mm)	PTH	Round
☼	26	12mil (0.305mm)	PTH	Round
◇	11	37.992mil (0.965mm)	PTH	Round
✪	24	39.37mil (1mm)	PTH	Round
⌑	35	40mil (1.016mm)	PTH	Round
▽	2	51.181mil (1.3mm)	PTH	Round
□	4	62mil (1.575mm)	PTH	Round
⊠	6	63mil (1.6mm)	PTH	Round
○	16	67mil (1.702mm)	PTH	Round
	507 Total			

Drill Table

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
2600MIL X 3200MIL

Number of Layers : 4
MIN. TRACK WIDTH: 7 MIL
MIN. CLEARANCE: 8 MIL
MIN. VIA PAD SIZE: 22 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
[ ] FR-408 [X] FR-4 High Tg [ ] OTHER
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
COPPER THICKNESS (FINISHED):
OUTER: [X] 1.4MIL (1oz) [ ] 2MIL (1.4oz) [ ] 2.8MIL (2oz)
INNER SIGNAL: [X] 1.4MIL (1oz) [ ] 2.8MIL (2oz) [ ] N/A
DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER
BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR:
[ ] GREEN [X] BLUE [ ] OTHER
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER
ARRAY/PANEL: [ ] CUT AND TRIM PER MECH LAYER 1
[ ] N.C. ROUTE [ ] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS --> [ ] 1 [X] 2 [ ] 3
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER
ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK

TEXAS INSTRUMENTS

PROJECT TITLE: TDC1000-GASEVM
DESIGNED FOR: Public Release
FILE NAME: SV601158A.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SV601158	REV: A	SVN REV: Not In VersionControl
LAYER NAME = [illegible]ions			
PLOT NAME = Fabrication Drawing	GENERATED : 12/18/2014 4:43:29 PM	TEXAS INSTRUMENTS	

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ENGINEER:	LAYOUT BY:
Bahram Mirshab	Krypton Solutions/RS
SCALE: 1.00	ALTIUM DESIGNER VERSION: 14.3.15.35511